Renesas Electronics America Inc - IDT79R3041-20PFG Datasheet

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Understanding Embedded - Microprocessors

Embedded microprocessors are specialized computing chips designed to perform specific tasks within an embedded system. Unlike general-purpose microprocessors found in personal computers, embedded microprocessors are tailored for dedicated functions within larger systems, offering optimized performance, efficiency, and reliability. These microprocessors are integral to the operation of countless electronic devices, providing the computational power necessary for controlling processes, handling data, and managing communications.

Applications of Embedded - Microprocessors

Embedded microprocessors are utilized across a broad spectrum of applications, making them indispensable in

Details	
Product Status	Obsolete
Core Processor	MIPS-I
Number of Cores/Bus Width	1 Core, 32-Bit
Speed	20MHz
Co-Processors/DSP	System Control; CP0
RAM Controllers	DRAM
Graphics Acceleration	No
Display & Interface Controllers	-
Ethernet	-
SATA	-
USB	-
Voltage - I/O	5.0V
Operating Temperature	0°C ~ 85°C (TC)
Security Features	-
Package / Case	100-LQFP
Supplier Device Package	100-TQFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/idt79r3041-20pfg

System Control Co-Processor

The R3041 also integrates on-chip a System Control Co-processor, CP0. CP0 manages the exception handling capability of the R3041, the virtual to physical address mapping of the R3041, and the programmable bus interface capabilities of the R3041. These topics are discussed in subsequent sections.

The R3041 does not include the optional TLB found in other members of the RISController family, but instead performs the same virtual to physical address mapping of the base version of the RISController family. These devices still support distinct kernel and user mode operation, but do not require page management software or an on-chip TLB, leading to a simpler software model and a lower-cost processor.

The memory mapping used by these devices is illustrated in Figure 3. Note that the reserved address spaces shown are for compatibility with future family members; in the current family members, references to these addresses are translated in the same fashion as their respective segments, with no traps or exceptions taken.

When using the base versions of the architecture, the system designer can implement a distinction between the user tasks and the kernel tasks, without having to execute page management software. This distinction can take the form of physical memory protection, accomplished by address decoding, or in other system specific forms. In systems which do not wish to implement memory protection, and wish to have the kernel and user tasks operate out of a single unified memory space, upper address lines can be ignored by the address decoder, and thus all references will be seen in the lower gigabyte of the physical address space.

The R3041 adds additional resources into the on-chip CP0. These resources are detailed in the R3041 User's Manual. They allow kernel software to directly control activity of the processor internal resources and bus interface, and include:

- **Cache Configuration Register:** This register controls the data cache block size and miss refill algorithm.
- **Bus Control Register:** This register controls the behavior of the various bus interface signals.
- **Count and Compare Registers:** Together, these two registers implement a programmable 24-bit timer, which can be used for DRAM refresh or as a general purpose timer.
- **Port Size Control Register:** This register allows the kernel to indicate the port width of reads and writes to various sub-regions of the physical address space. Thus, the R3041 can interface directly with 8-, 16-, and 32-bit memory ports, including a mix of sizes, for both instruction and data references, without requiring additional external logic.

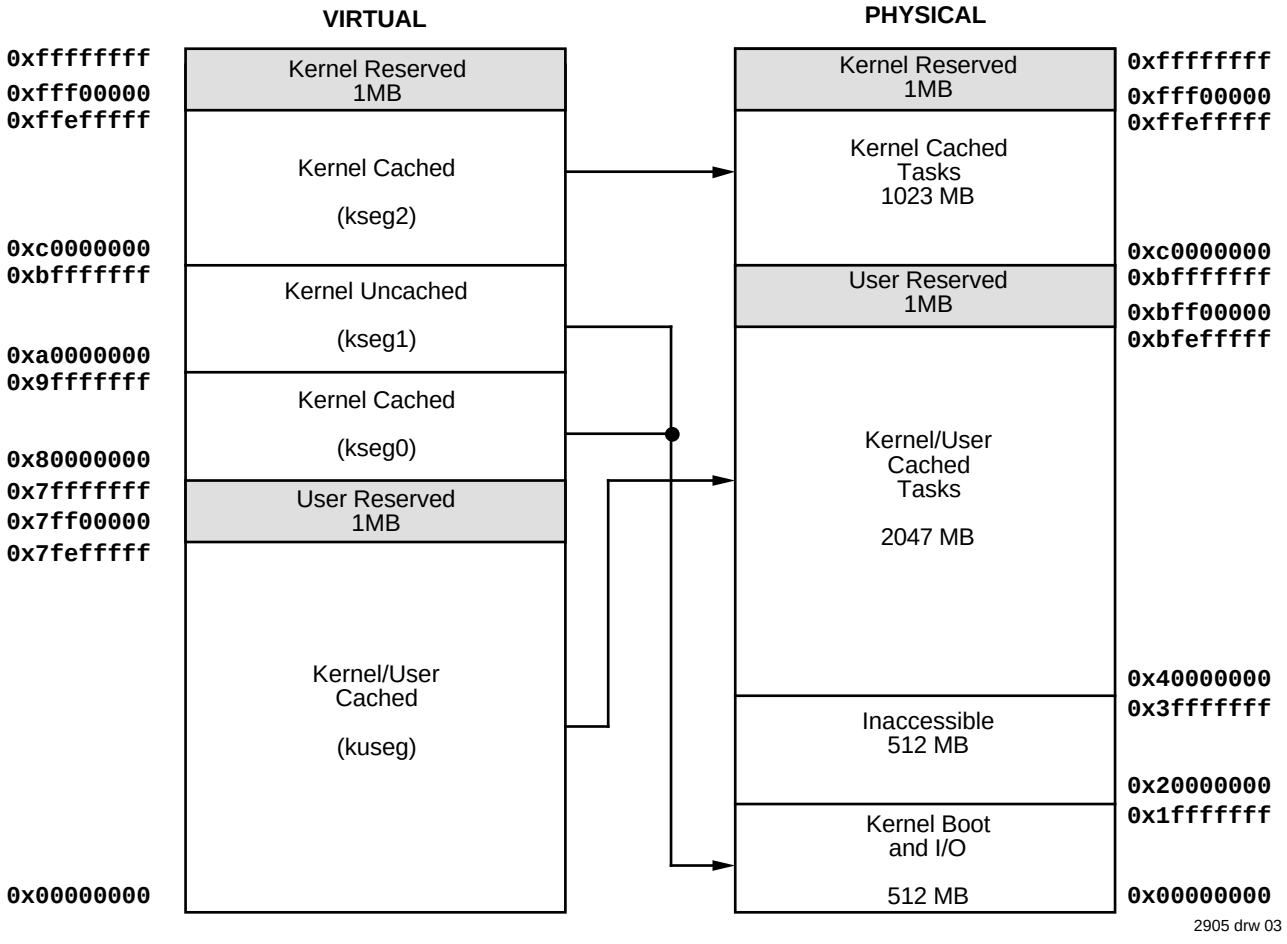


Figure 3. Virtual to Physical Mapping of Base Architecture Versions

DEVELOPMENT SUPPORT

The IDT RISController family is supported by a rich set of development tools, ranging from system simulation tools through PROM monitor and debug support, applications software and utility libraries, logic analysis tools, and sub-system modules.

Figure 5 is an overview of the system development process typically used when developing R3041 applications. The RISController family is supported in all phases of project development. These tools allow timely, parallel development of hardware and software for RISController family based applications, and include tools such as:

- Optimizing compilers from MIPS Technology, the acknowledged leader in optimizing compiler technology.
- Cross development tools, available in a variety of development environments.
- The high-performance IDT floating point emulation library software.
- The IDT Evaluation Board, which includes RAM, EPROM, I/O, and the IDT PROM Monitor.
- IDT Laser Printer System boards, which directly drive a low-cost print engine, and runs Adobe PostScript™ Page Description Language
- Adobe PostScript Page Description Language running on the IDT RISController family.
- The IDT/sim™ PROM Monitor, which implements a full PROM monitor (diagnostics, remote debug support, peek/

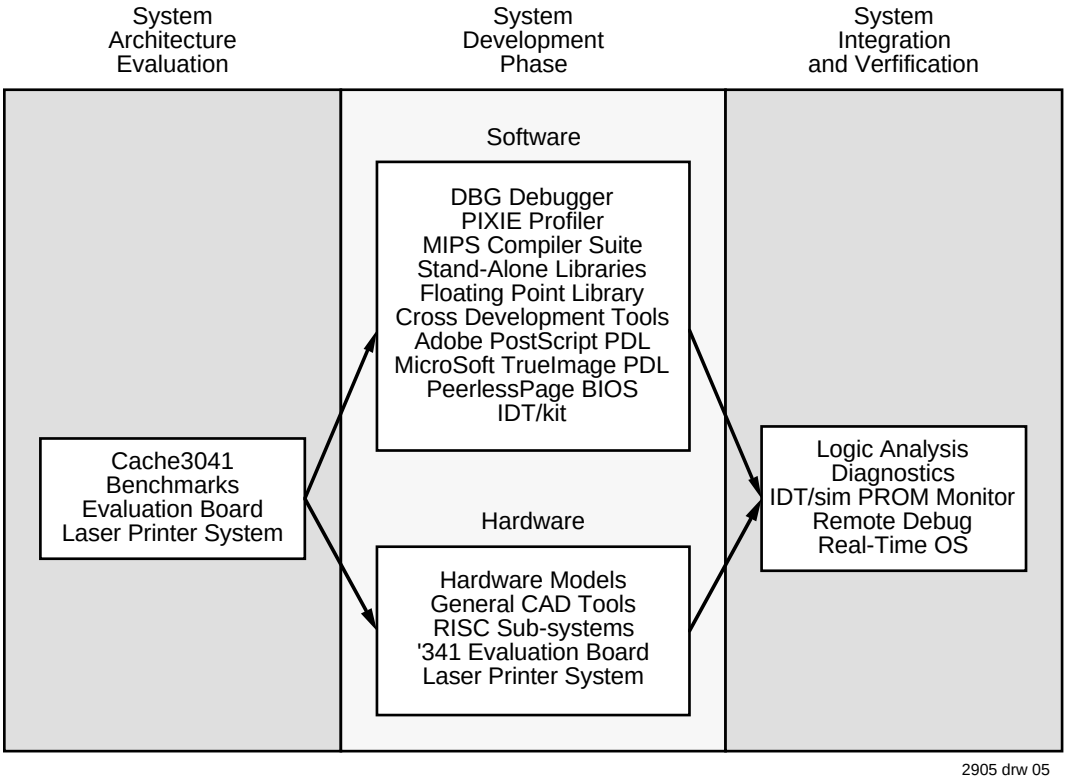


Figure 5. R3041 Development Environment

- **Programmable memory Port Widths**: The R3041 allows the kernel to partition the physical memory space into various sub-regions, and to individually indicate the port width of these sub-regions. Thus, the bus interface unit can perform data packing and unpacking when communicating with narrow memory sub-regions. For example, these features, can be used to allow the R3041 to interface with narrow 8-bit boot PROMs, or to implement 16-bit only memory systems.

THERMAL CONSIDERATIONS

The RISController family utilizes special packaging techniques to improve the thermal properties of high-speed processors. Thus, all versions of the RISController family are packaged in cavity down packaging.

The lowest cost members of the family use a standard cavity down, injection molded PLCC package (the “J” package). This package is used for all speeds of the R3041 family.

Higher speed and higher performance members of the RISController family utilize more advanced packaging techniques to dissipate power while remaining both low-cost and pin- and socket- compatible with the PLCC package. Thus, these members of the RISController family are available in the MQUAD package (the “MJ” package), which is an all aluminum package with the die attached to a normal copper leadframe mounted to the aluminum casing. The MQUAD package is pin and form compatible with the PLCC package. Thus, designers can choose to utilize this package without changing their PCB.

	Airflow (ft/min)					
ØCA	**0**	**200**	**400**	**600**	**800**	**1000**
"J" Package	29	26	21	18	16	15
TQFP	55	40	35	33	31	30

2905 tbl 02

Table 2. Thermal Resistance (ØCA) at Various Airflows

The members of the RISController family are guaranteed in a case temperature range of 0°C to +85°C. The type of package, speed (power) of the device, and airflow conditions, affect the equivalent ambient conditions which meet this specification.

The equivalent allowable ambient temperature, T_A, can be calculated using the thermal resistance from case to ambient ($Ø_{CA}$) of the given package. The following equation relates ambient and case temperature:

$$T_A = T_C - P * Ø_{CA}$$

where P is the maximum power consumption at hot temperature, calculated by using the maximum Icc specification for the device.

Typical values for $Ø_{CA}$ at various airflows are shown in Table 2 for the PLCC package.

NOTES ON SYSTEM DESIGN

The R3041 has been designed to simplify the task of high-speed system design. Thus, set-up and hold-time requirements have been kept to a minimum, allowing a wide variety of system interface strategies.

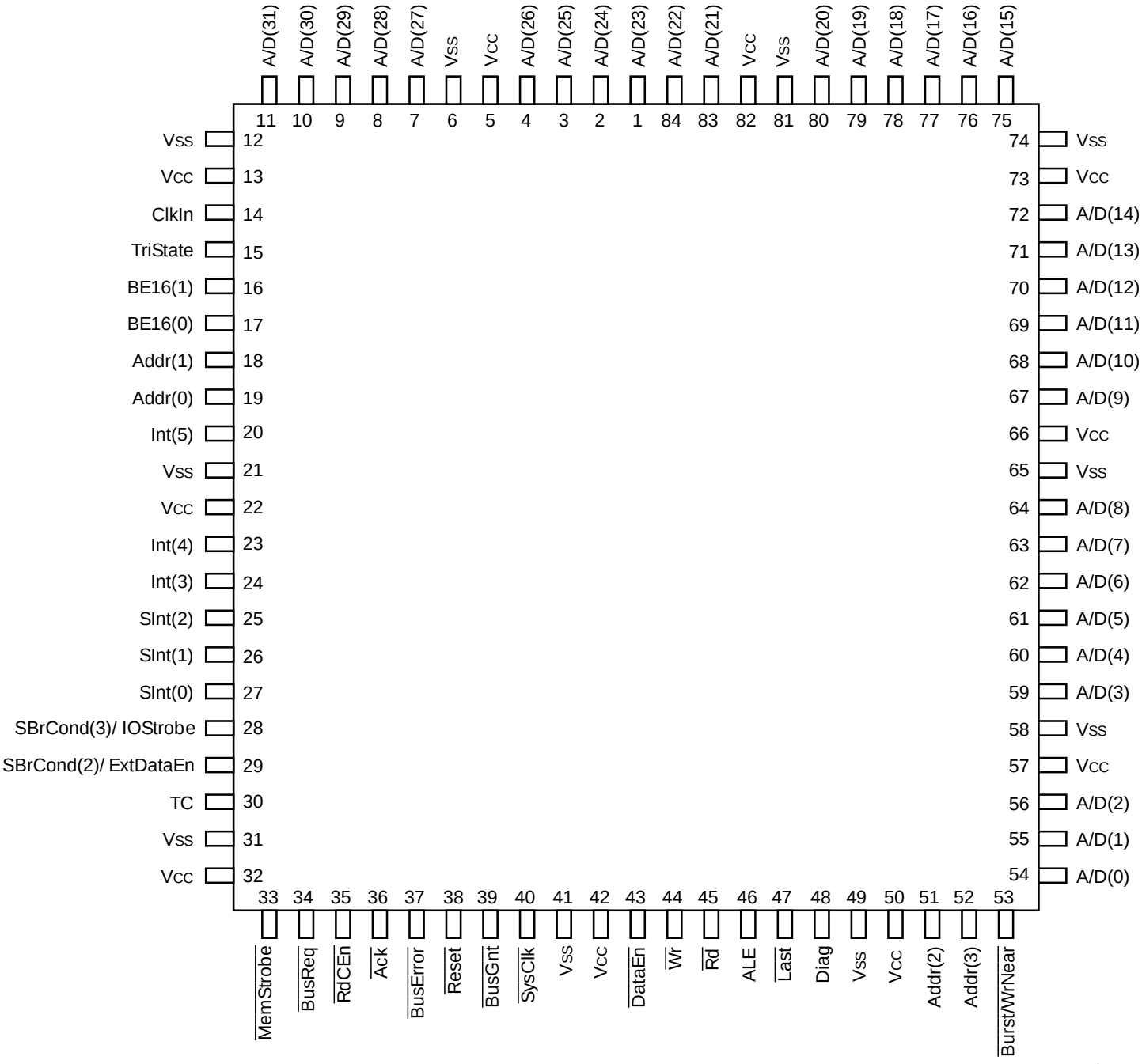
To minimize these AC parameters, the R3041 employs feedback from its SysClk output to the internal bus interface unit. This allows the R3041 to reference input signals to the reference clock seen by the external system. The SysClk output is designed to provide relatively large AC drive to minimize skew due to slow rise or fall times. A typical part will have less than 2ns rise or fall (10% to 90% signal times) when driving the test load.

Therefore, the system designer should use care when designing for direct SysClk use. Total loading (due to devices connected on the signal net and the routing of the net itself) should be minimized to ensure the SysClk output has a smooth and rapid transition. Long rise and/or fall times may cause a degradation in the speed capability of an individual device.

Similarly, the R3041 employs feedback on its ALE output to ensure adequate address hold time to ALE. The system designer should be careful when designing the ALE net to minimize total loading and to minimize skew between ALE and the A/D bus, which will ensure adequate address access latch time.

IDT's field and factory applications groups can provide the system designer with assistance for these and other design issues.

PIN CONFIGURATIONS

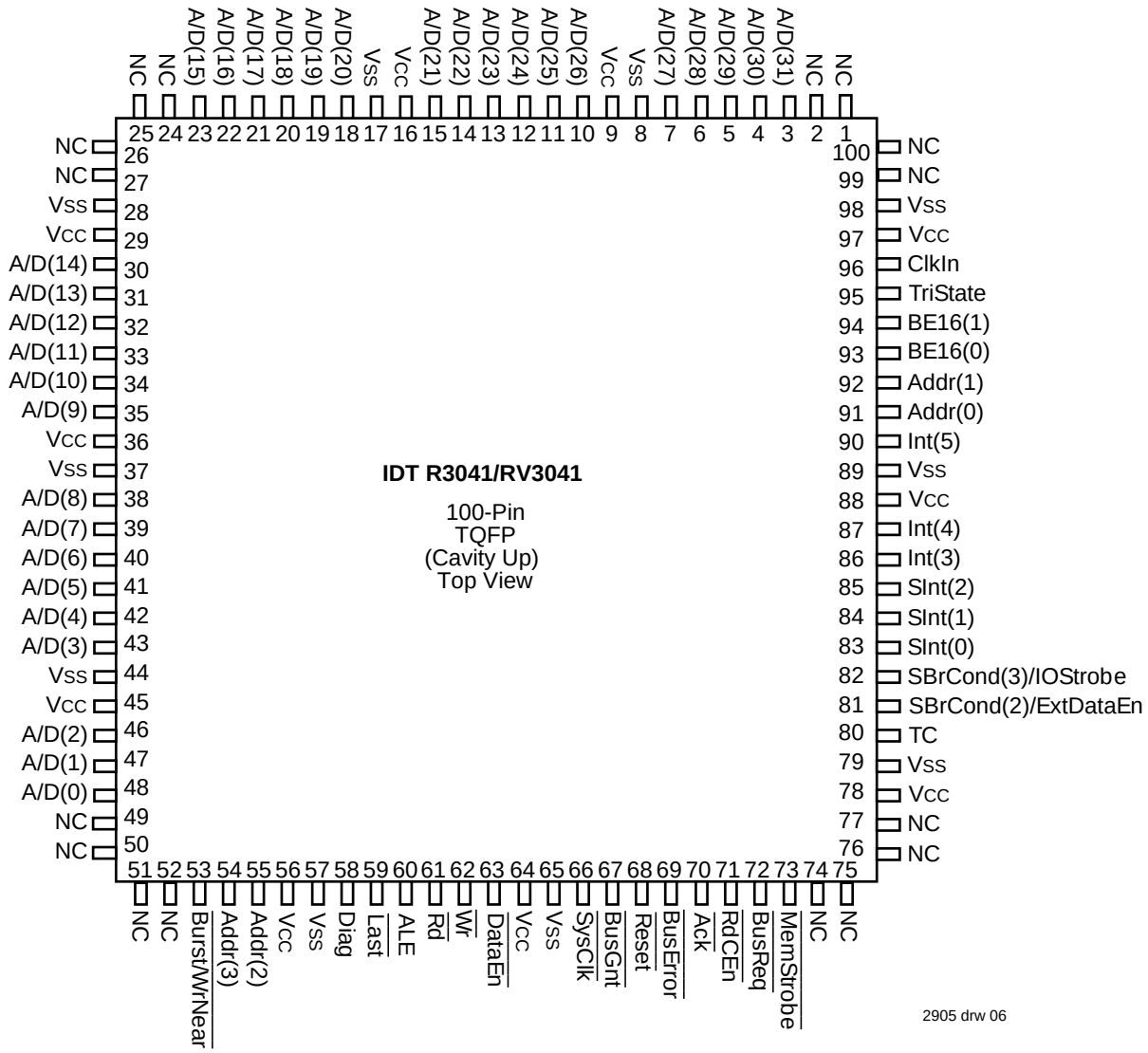


2905 drw 06

84-Pin PLCC/
Top View

(Cavity Down)

PIN CONFIGURATIONS



2905 drw 06

PIN DESCRIPTION

PIN NAME	I/O	DESCRIPTION
A/D(31:0)	I/O	**Address/Data:** A 32-bit time multiplexed bus which indicates the desired address for a bus transaction in one phase, and which is used to transmit data between the CPU and external memory resources during the rest of the transfer. Bus transactions on this bus are logically separated into two phases: during the first phase, information about the transfer is presented to the memory system to be captured using the ALE output. This information consists of: **Address(31:4)**: The high-order address for the transfer is presented on A/D(31:4). $\overline{BE(3:0)}$: These strobes indicate which bytes of the 32-bit bus will be involved in the transfer, and are presented on A/D(3:0). $\overline{BE(3)}$ indicates that A/D(31:24) will be used, and $\overline{BE(0)}$ corresponds to A/D(7:0). These strobes are only valid for accesses to 32-bit wide memory ports. Note that $\overline{BE(3:0)}$ can be held in-active during reads by setting the appropriate bit of CP0; thus when latched, these signals can be directly used as Write Enable strobes. During the second phase, these signals are the data bus for the transaction. **Data(31:0):** During write cycles, the bus contains the data to be stored and is driven from the internal write buffer. On read cycles, the bus receives the data from the external resource, in either a single data transaction or in a burst of four words, and places it into the on-chip read buffer. The byte lanes used during the transfer are a function of the datum size, the memory port width, and the system byte-ordering.
Addr(3:0)	O I[1]	**Low Address (3:0)** A 4-bit bus which indicates which word/halfword/byte is currently expected by the processor. For 32-bit port widths, only Addr(3:2) is valid during the transfer; for 16-bit port widths, only Addr(3:1) are valid; for 8-bit port widths, all of Addr(3:0) are valid. These address lines always contain the address of the current datum to be transferred. In writes and single datum reads, the addresses initially output the specific target address, and will increment if the size of the datum is wider than the target memory port. For quad word reads, these outputs function as a counter starting at '0000', and incrementing according to the width of the memory port. During $\overline{Reset}$, the Addr(3:0) pins act as Reset Configuration Mode bit inputs for the $\overline{BootProm16}$, $\overline{BootProm8}$, ReservedHigh, and $\overline{ExtAddrHold}$ options. The R3041 Addr(1:0) output pins are designated as the unconnected Rsvd(1:0) pins in the R3051 and R3081.
Diag	O	**Diagnostic Pin.** This output indicates whether the current bus read transaction is due to an on-chip cache miss and whether the read is an instruction or data. It is time multiplexed as described below: **Cached/**$\overline{Uncached}$**:** During the phase in which the A/D bus presents address information, this pin is an active high output which indicates whether or not the current read is a result of a cache miss. The value of this pin at this time other than in read cycles is undefined. **I/**$\overline{D}$: A high at this time indicates an instruction reference, and a low indicates a data reference. The value of this pin at this time other than in read cycles is undefined. The R3041 Diag output pin is designated as the Diag(1) output pin in the R3051 and R3081.
ALE	O	**Address Latch Enable:** Used to indicate that the A/D bus contains valid address information for the bus transaction. This signal is used by external logic to capture the address for the transfer, typically by using transparent latches.
$\overline{DataEn}$	O	**Data Enable:** This signal indicates that the A/D bus is no longer being driven by the processor during read cycles, and thus the external memory system may enable the drivers of the memory system onto this bus without having a bus conflict occur. During write cycles, or when no bus transaction is occurring, this signal is negated, thus disabling the external memory drivers.

NOTE:
1. Reset Configuration Mode bit input when $\overline{Reset}$ is asserted, normal signal function when $\overline{Reset}$ is de-asserted.

2905 tbl 03

PIN DESCRIPTION (Continued):

PIN NAME	I/O	DESCRIPTION
Burst/ WrNear	O	**Burst Transfer/Write Near:** On read transactions, the Burst signal indicates that the current bus read is requesting a block of four contiguous words from memory. This signal is asserted only in read cycles due to cache misses; it is asserted for all I-Cache miss read cycles, and for D-Cache miss read cycles if the 4-word data block refill option is selected in the CP0 Cache Config Register. On write transactions, the WrNear output tells the external memory system that the bus interface unit is performing back-to-back write transactions to an address within the same 256 byte page as the prior write transaction. This signal is useful in memory systems which employ page mode or static column DRAMs, and allows nearby writes to be retired quickly.
Rd	O	**Read:** An output which indicates that the current bus transaction is a read.
Wr	O	**Write:** An output which indicates that the current bus transaction is a write.
Ack	I	**Acknowledge:** An input which indicates to the device that the memory system has sufficiently processed the bus transaction. On write transactions, this signal indicates that the CPU may either progress to the next data item (for mini-burst writes of wide datums to narrow memories), or terminate the write cycle. On read transactions, this signal indicates that the memory system has sufficiently processed the read, and that the processor core may begin processing the data from this read transfer.
RdCEn	I	**Read Buffer Clock Enable:** An input which indicates to the device that the memory system has placed valid data on the A/D bus, and that the processor may move the data into the on-chip Read Buffer.
SysClk	O	**System Reference Clock:** An output from the CPU which reflects the timing of the internal processor "System" clock. This clock is used to control state transitions in the read buffer, write buffer, memory controller, and bus interface unit.
BusReq	I	**DMA Arbiter Bus Request:** An input to the device which requests that the CPU tri-state its bus interface signals so that they may be driven by an external master. The negation of this input relinquishes mastership back to the CPU.
BusGnt	O	**DMA Arbiter Bus Grant.** An output from the CPU used to acknowledge that a BusReq has been detected, and that the bus is relinquished to the external master. The R3041 adds an additional DMA protocol, under the control of CP0. If the DMA Protocol is enabled, the R3041 can request that the external master relinquish bus mastership back to the processor by negating the BusGnt output early, and waiting for the BusReq input to be negated.
SBrCond(3)/ IOStrobe	I/O	**Branch Condition Port/IO Strobe:** The use of this signal depends on the setting of various bits of the CP0 Bus Control register. If BrCond mode is selected, this input is logically connected to CpCond(3), and can be used by the branch on co-processor condition instructions as an input port. The SBrCond(3) input has special internal logic to synchronize the input, and thus may be driven by asynchronous agents. If this pin is selected to function as IOStrobe, it may be asserted as an output on reads, writes, or both, as programmed into CP0. This strobe asserts in the second clock cycle of a transfer, and thus can be used to strobe various control signals on the bus interface.
SBrCond(2)/ ExtDataEn	I/O	**Branch Condition Port/Extended Data Enable:** The use of this signal depends on the settings in the CP0 Bus Control register. If BrCond mode is selected, this input is logically connected to CpCond(2), and can be used by the branch on co-processor condition instructions as an input port. The SBrCond(2) input has special internal logic to synchronize the input, and thus may be driven by asynchronous agents. If this pin is selected to function as Extended Data Enable, it may be asserted as an output on reads, writes, or both, as programmed into CP0. This strobe can be used as an extended data enable strobe, in that it is held asserted for one-half clock cycle after the negation of Rd or Wr. This signal may typically be used as a write enable control line for transceivers, as a write line for I/O, or as an address mux select for DRAMs.
MemStrobe	O	**Memory Strobe:** This active low output pulses low for each data read or written, as configured in the CP0 Bus Control register. Thus, it can be used as a read strobe, write strobe, or both, for SRAM type memories or for I/O devices. The R3041 MemStrobe output pin is designated as the BrCond(0) input pin in the R3051 and R3081.

2905 tbl 04

ABSOLUTE MAXIMUM RATINGS(1, 3) R3041

Symbol	Rating	Commercial	Unit
V_{TERM}	Terminal Voltage with Respect to GND	–0.5 to +7.0	V
T_C	Operating Case Temperature	0 to +85	°C
T_{BIAS}	Temperature Under Bias	–55 to +125	°C
T_{STG}	Storage Temperature	–55 to +125	°C
V_{IN}	Input Voltage	–0.5 to +7.0	V

2905 tbl 06

NOTES:
1. Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.
2. V_{IN} minimum = –3.0V for pulse width less than 15ns. V_{IN} should not exceed V_{CC} +0.5 Volts.
3. Not more than one output should be shorted at a time. Duration of the short should not exceed 30 seconds.

AC TEST CONDITIONS R3041

Symbol	Parameter	Min.	Max.	Unit
V_{IH}	Input HIGH Voltage	3.0	—	V
V_{IL}	Input LOW Voltage	—	0	V
V_{IHS}	Input HIGH Voltage	3.5	—	V
V_{ILS}	Input LOW Voltage	—	0	V

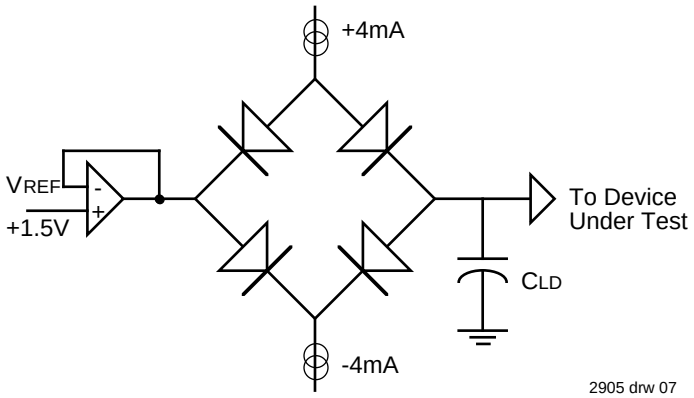
2905 tbl 08

RECOMMENDED OPERATING TEMPERATURE AND SUPPLY VOLTAGE

Grade	Temperature	GND	Vcc
Commercial	0°C to +85°C (Case)	0V	5.0 ±5%

2905 tbl 07

OUTPUT LOADING FOR AC TESTING



2905 drw 07

Signal	Cld
All Signals	25 pF

2905 tbl 09

DC ELECTRICAL CHARACTERISTICS R3041 — (T_C = 0°C to +85°C, V_{CC} = +5.0V ±5%)

Symbol	Parameter	Test Conditions	16.67MHz		20MHz		25MHz		33MHz		Unit
			Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
V_{OH}	Output HIGH Voltage	V_{CC} = Min., I_{OH} = –4mA	3.5	—	3.5	—	3.5	—	3.5	—	V
V_{OL}	Output LOW Voltage	V_{CC} = Min., I_{OL} = 4mA	—	0.4	—	0.4	—	0.4	—	0.4	V
V_{IH}	Input HIGH Voltage(3)	—	2.0	—	2.0	—	2.0	—	2.0	—	V
V_{IL}	Input LOW Voltage(1)	—	—	0.8	—	0.8	—	0.8	—	0.8	V
V_{IHS}	Input HIGH Voltage(2,3)	—	3.0	—	3.0	—	3.0	—	3.0	—	V
V_{ILS}	Input LOW Voltage(1,2)	—	—	0.4	—	0.4	—	0.4	—	0.4	V
C_{IN}	Input Capacitance(4)	—	—	10	—	10	—	10	—	10	pF
C_{OUT}	Output Capacitance(4)	—	—	10	—	10	—	10	—	10	pF
I_{CC}	Operating Current	V_{CC} = 5V, T_C = 25°C	—	225	—	250	—	300	—	370	mA
I_{IH}	Input HIGH Leakage	V_{IH} = VCC	—	100	—	100	—	100	—	100	µA
I_{IL}	Input LOW Leakage	V_{IL} = GND	–100	—	–100	—	–100	—	–100	—	µA
I_{OZ}	Output Tri-state Leakage	V_{OH} = 2.4V, V_{OL} = 0.5V	–100	100	–100	100	–100	100	–100	100	µA

2905 tbl 10

NOTES:
1. V_{IL} Min. = –3.0V for pulse width less than 15ns. V_{IL} should not fall below –0.5 volts for larger periods.
2. V_{IHS} and V_{ILS} apply to ClkIn and $\overline{\text{Reset}}$.
3. V_{IH} should not be held above V_{CC} + 0.5 volts.
4. Guaranteed by design.

AC ELECTRICAL CHARACTERISTICS RV3041 (CONT.)

Symbol	Signals	Description	16.67 MHz		20 MHz		25MHz		33MHz		Unit
			Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
t18	A/D	Tri-state from $\overline{\text{SysClk}}$	—	13	—	10	—	10	—	10	ns
t19	A/D	$\overline{\text{SysClk}}$ to data out	—	16	—	13	—	12	—	12	ns
t20	ClkIn	Pulse Width High	12	—	10	—	8	—	6.5	—	ns
t21	ClkIn	Pulse Width Low	12	—	10	—	8	—	6.5	—	ns
t22	ClkIn	Clock Period	30	250	25	250	20	250	15	250	ns
t23	$\overline{\text{Reset}}$	Pulse Width from Vcc valid	200	—	200	—	200	—	200	—	µs
t24	$\overline{\text{Reset}}$	Minimum Pulse Width	32	—	32	—	32	—	32	—	sys
t25	$\overline{\text{Reset}}$	Set-up to $\overline{\text{SysClk}}$ falling	8	—	6	—	5	—	5	—	ns
t26	$\overline{\text{Int}}$	Mode set-up to $\overline{\text{Reset}}$ rising	8	—	6	—	5	—	5	—	ns
t27	$\overline{\text{Int}}$	Mode hold from $\overline{\text{Reset}}$ rising	2.5	—	2.5	—	2.5	—	2.5	—	ns
t28	$\overline{\text{SInt}}$, SBrCond	Set-up to $\overline{\text{SysClk}}$ falling	8	—	6	—	5	—	5	—	ns
t29	$\overline{\text{SInt}}$, SBrCond	Hold from $\overline{\text{SysClk}}$ falling	4	—	3	—	3	—	3	—	ns
t30	$\overline{\text{Int}}$, BrCond	Set-up to $\overline{\text{SysClk}}$ falling	8	—	6	—	5	—	5	—	ns
t31	$\overline{\text{Int}}$, BrCond	Hold from $\overline{\text{SysClk}}$ falling	4	—	3	—	3	—	3	—	ns
tsys	$\overline{\text{SysClk}}$	Pulse Width	2*t22	2*t22	2*t22	2*t22	2*t22	2*t22	2*t22	2*t22	ns
t32	$\overline{\text{SysClk}}$	Clock High Time	t22 - 2	t22 + 2	t22 - 2	t22 + 2	t22 - 2	t22 + 2	t22 - 2	t22 + 2	ns
t33	$\overline{\text{SysClk}}$	Clock Low Time	t22 - 2	t22 + 2	t22 - 2	t22 + 2	t22 - 2	t22 + 2	t22 - 2	t22 + 2	ns
t45	$\overline{\text{ExtDataEn}}$	Tri-state from $\overline{\text{SysClk}}$ rising (after driven condition)	—	13	—	10	—	10	—	10	ns
t46	$\overline{\text{ExtDataEn}}$	Driven from $\overline{\text{SysClk}}$ falling (after driven condition)	—	13	—	10	—	10	—	10	ns
t47	$\overline{\text{IOStrobe}}$	Valid from $\overline{\text{SysClk}}$ falling	—	10	—	8	—	7	—	7	ns
t48	$\overline{\text{ExtDataEn}}$,	Asserted from $\overline{\text{SysClk}}$ rising	—	15	—	12	—	9	—	9	ns
t49	$\overline{\text{ExtDataEn}}$ $\overline{\text{DataEn}}$	Negated from $\overline{\text{SysClk}}$ rising	—	9	—	7	—	6	—	6	ns
t50	$\overline{\text{MemStrobe}}$	Asserted from $\overline{\text{SysClk}}$ rising	—	19	—	15	—	15	—	15	ns
t51	$\overline{\text{MemStrobe}}$	Negated from $\overline{\text{SysClk}}$ falling	—	19	—	15	—	15	—	15	ns
t52	$\overline{\text{MemStrobe}}$	Asserted from Addr(3:0) valid(4)	0	—	0	—	0	—	0	—	ns
tderate	All outputs	Timing deration for loading over 25pF(4, 5)	—	0.5	—	0.5	—	0.5	—	0.5	ns/ 25pF

NOTES:

2905 tbl 12

1. All timings referenced to 1.5 Volts, with a rise and fall time of less than 2.5ns.
2. All outputs tested with 25pF loading.
3. The AC values listed here reference timing diagrams contained in the R3041 Hardware User's Manual.
4. Guaranteed by design.
5. This parameter is used to derate the AC timings according to the loading of the system. This parameter provides a deration for loads over the specified test condition; that is, the deration factor is applied for each 25pF over the specified test load condition.
6. Timings t34 - t44 are reserved for other RISController family members.

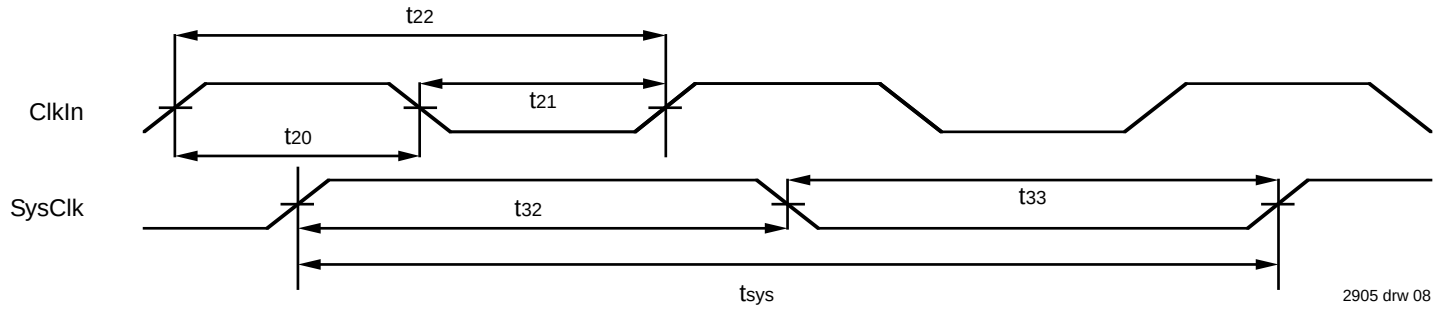


Figure 8. RISController Family Clocking

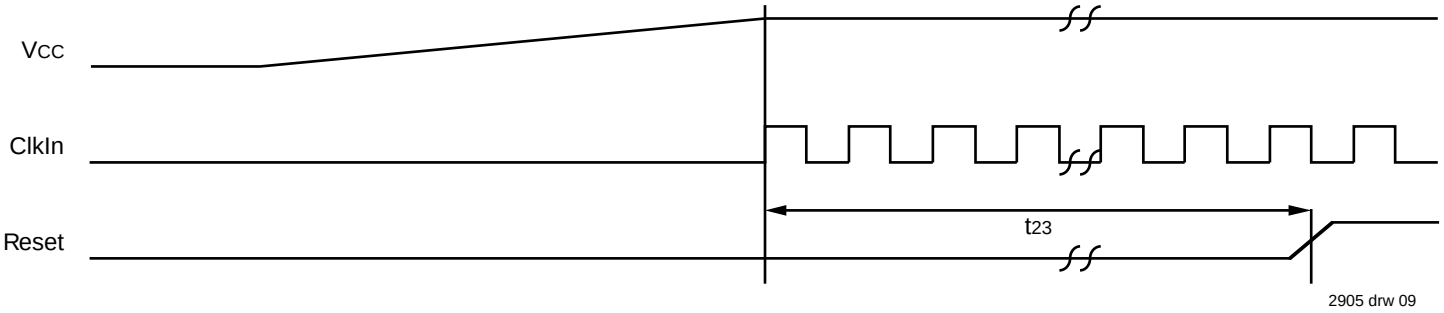


Figure 9. Power-On Reset Sequence

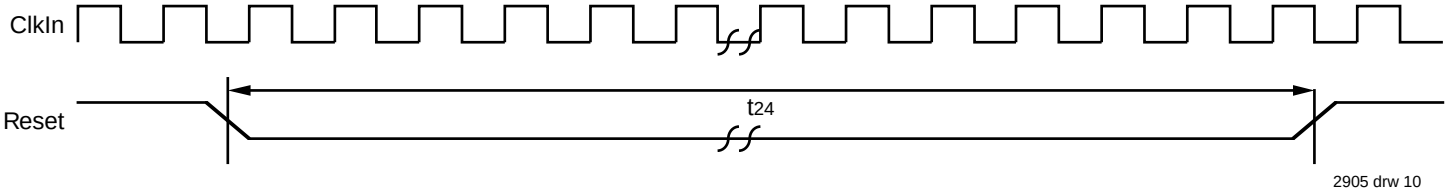


Figure 10(a). Warm Reset Sequence

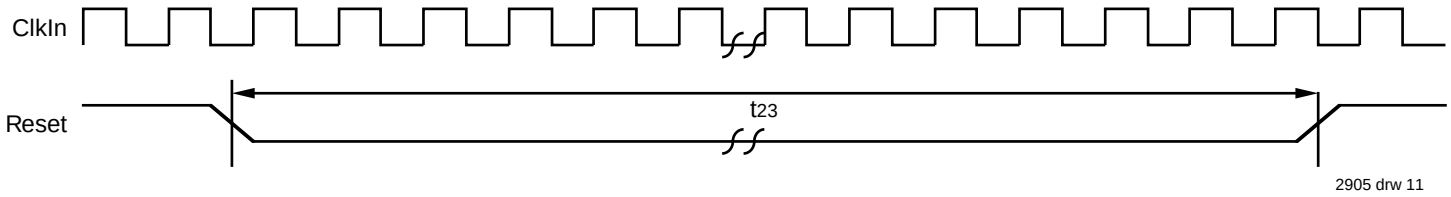


Figure 10(b). Warm Reset Sequence (Internal Pull-Ups Used)

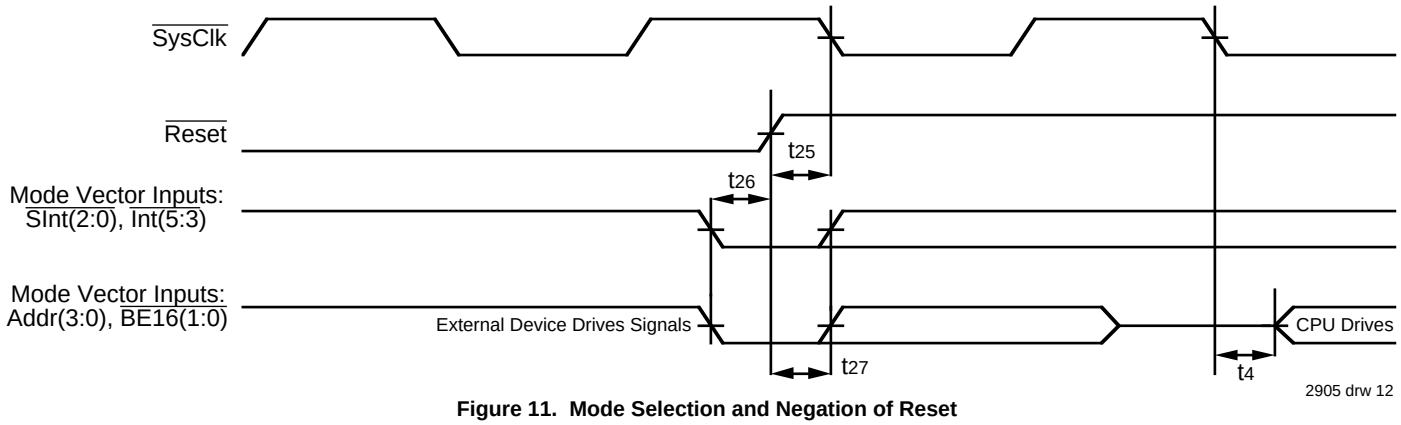


Figure 11. Mode Selection and Negation of Reset

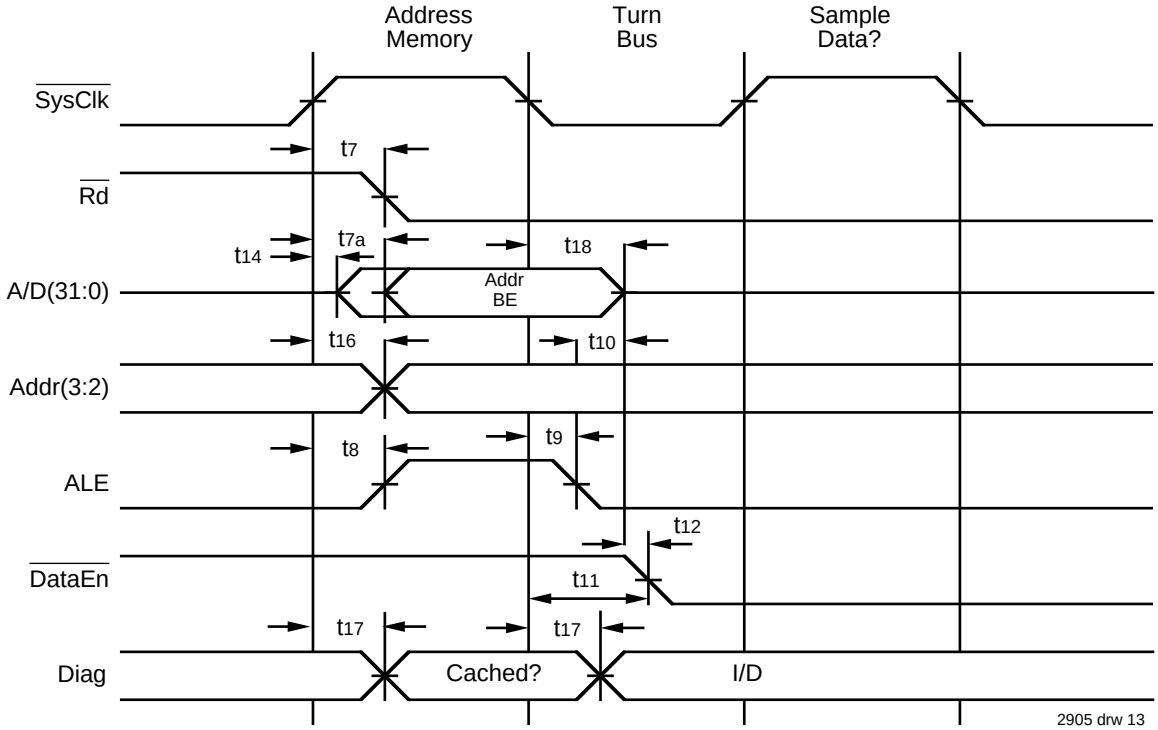


Figure 12(a). Start of Read Timing with Non-Extended Address Hold Option

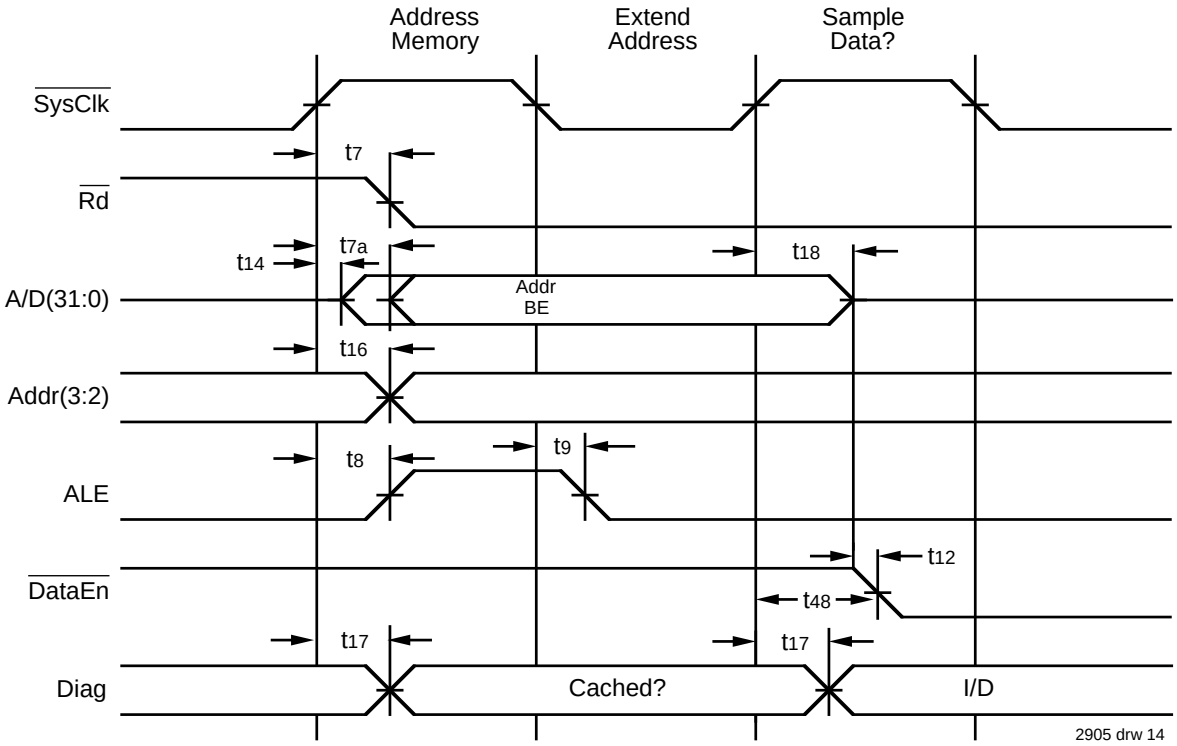


Figure 12(b). Start of Read Timing with Extended Address Hold Option

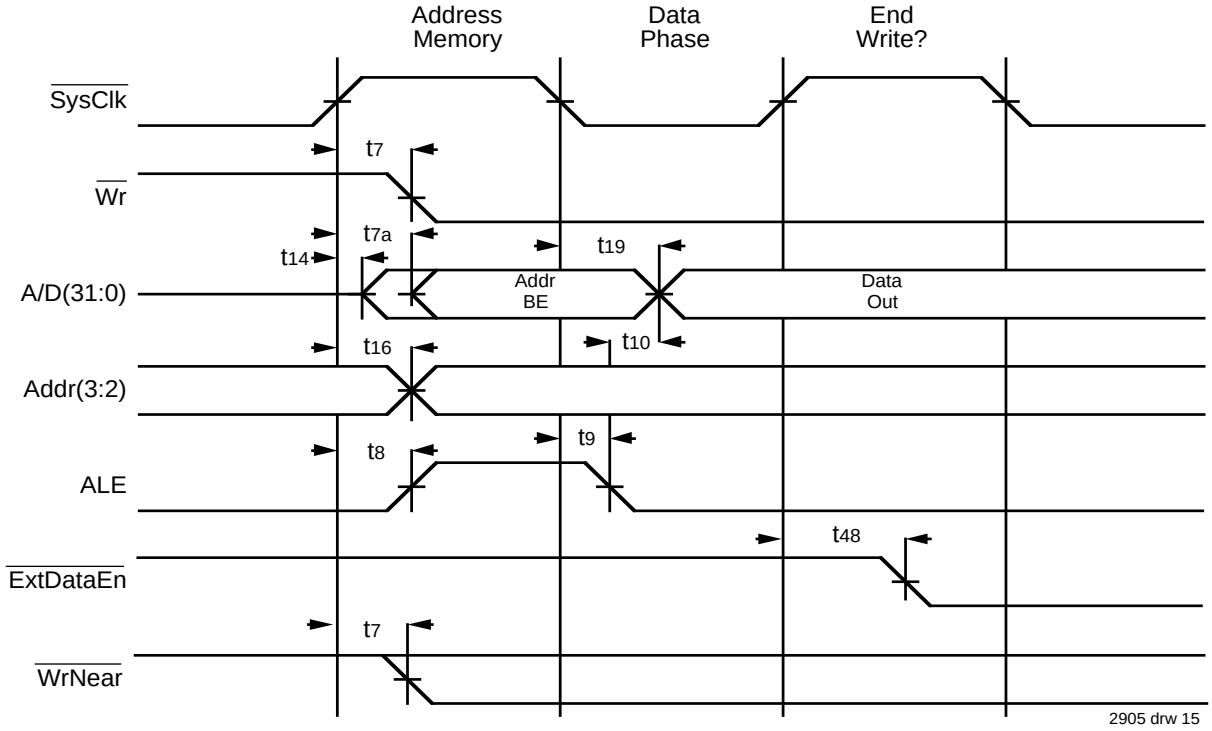


Figure 12(c). Start of Write Timing with Non-Extended Address Hold Option

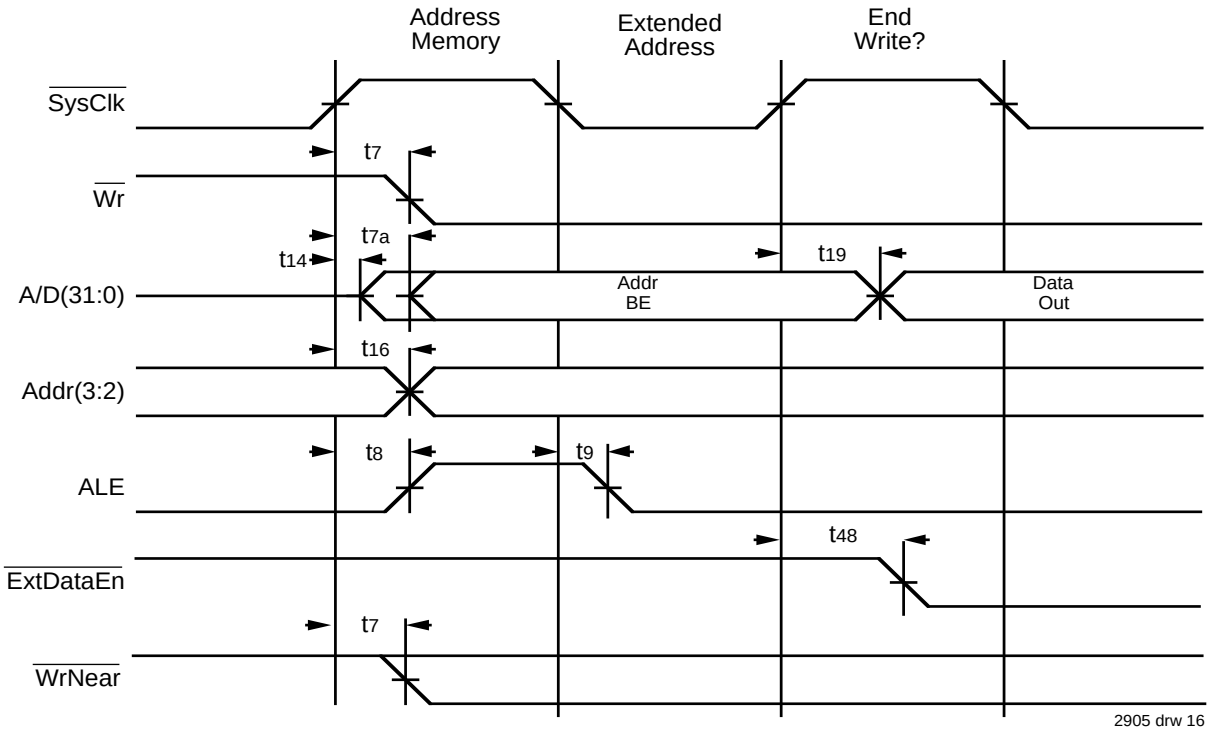


Figure 12(d). Start of Write Timing with Extended Address Hold Option

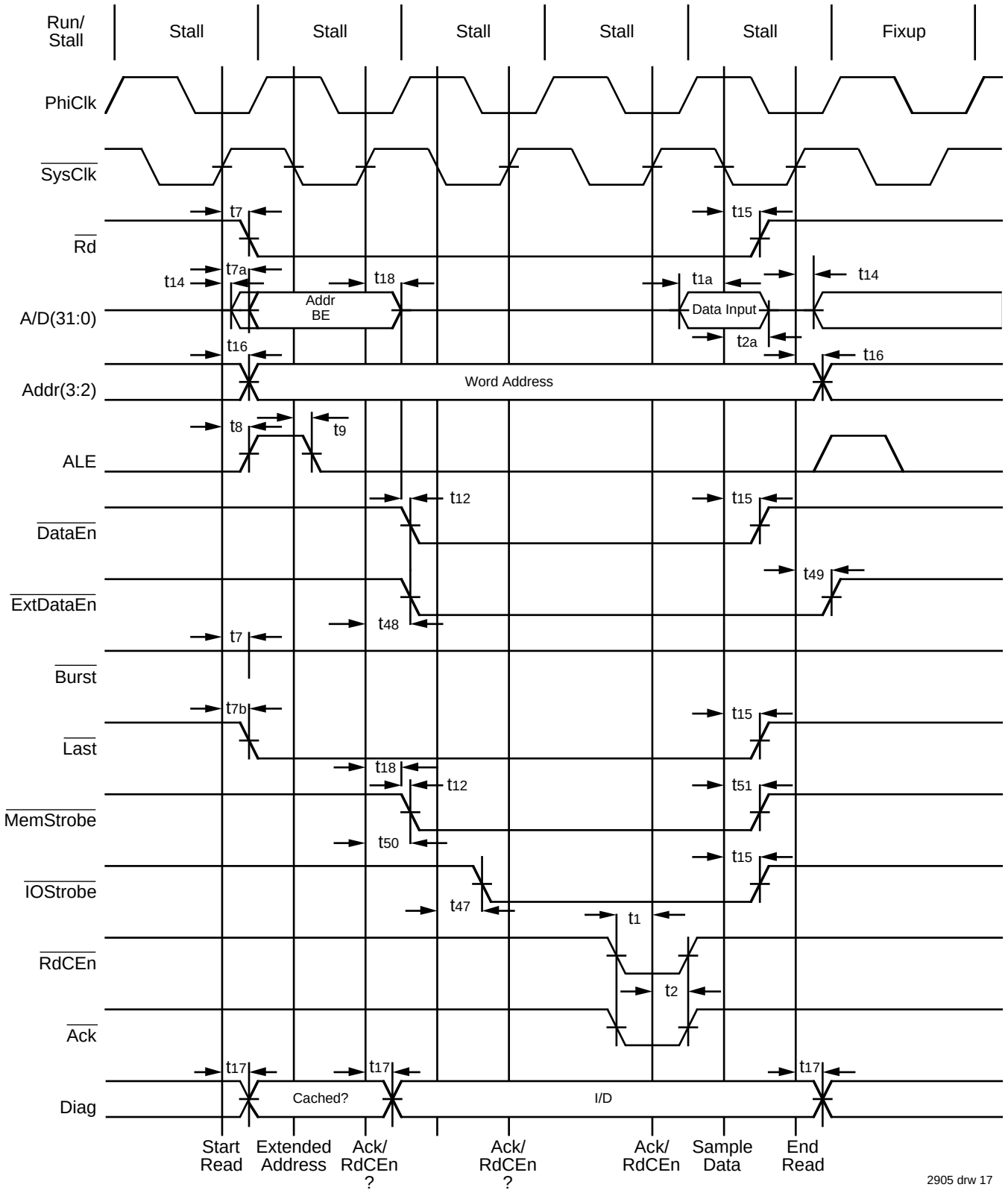


Figure 13. Single Datum Read

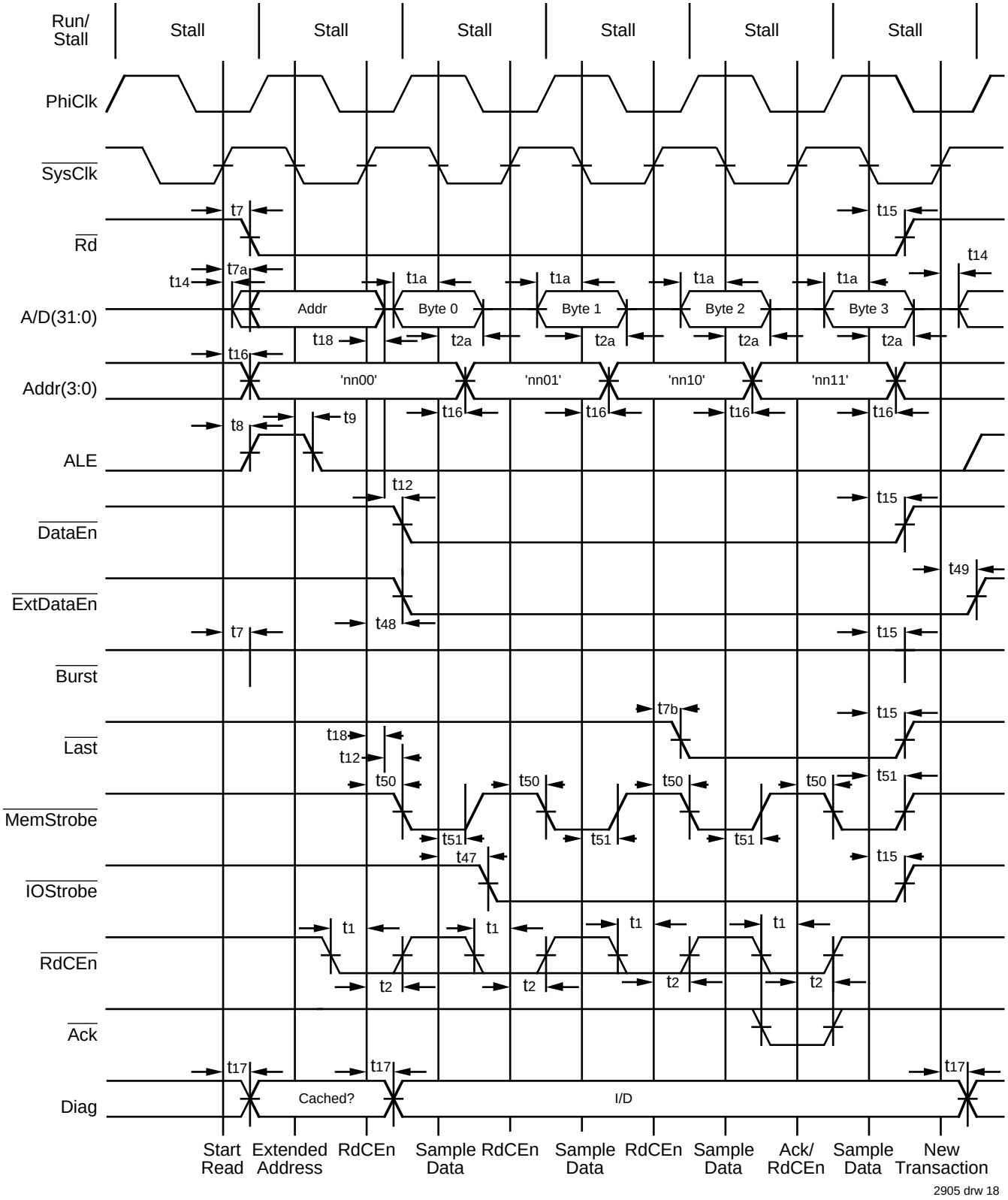


Figure 14. Mini-burst read of 32-bit datum from 8-bit wide memory port

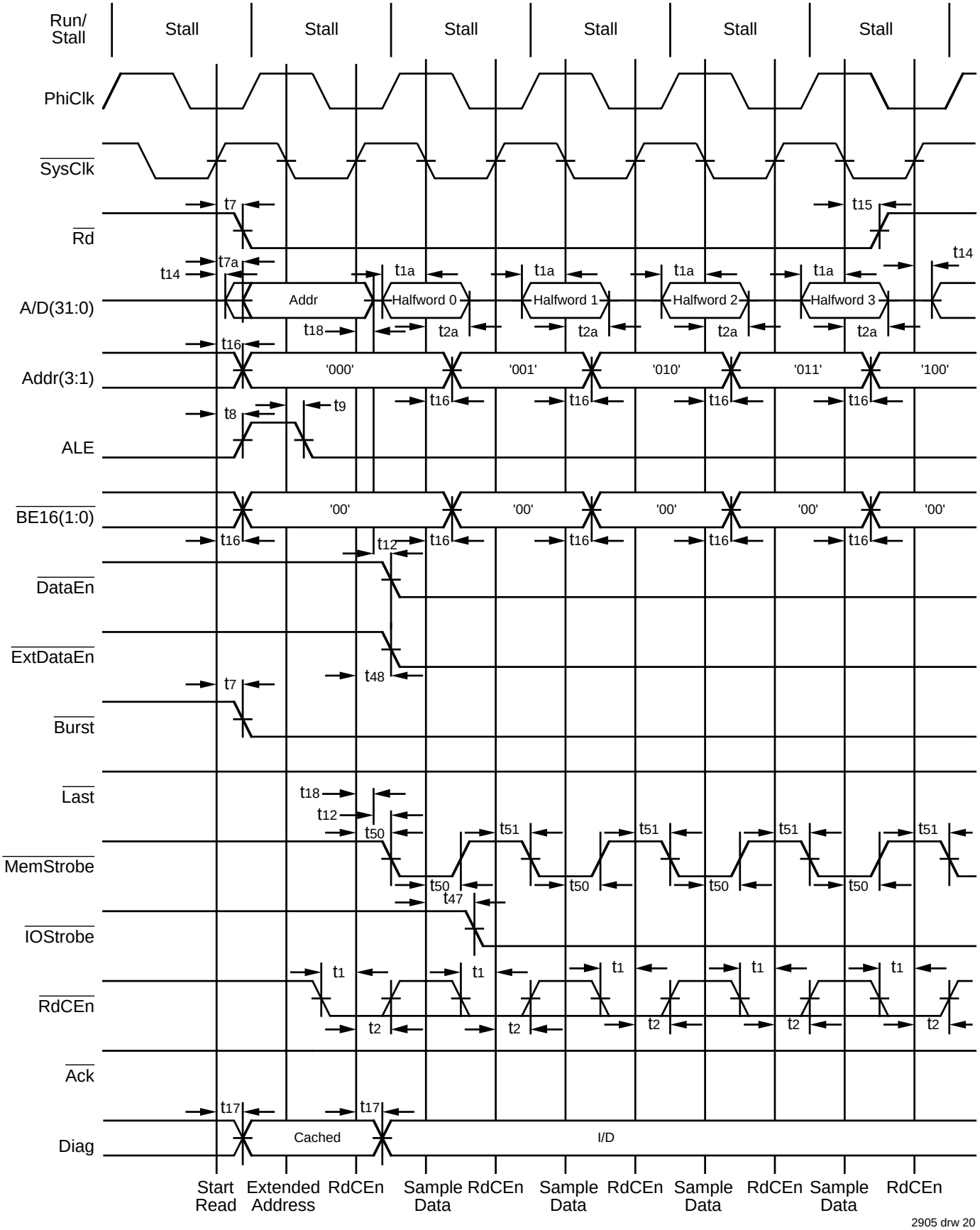


Figure 16(a). Quad Word Read to 16-bit wide Memory Port

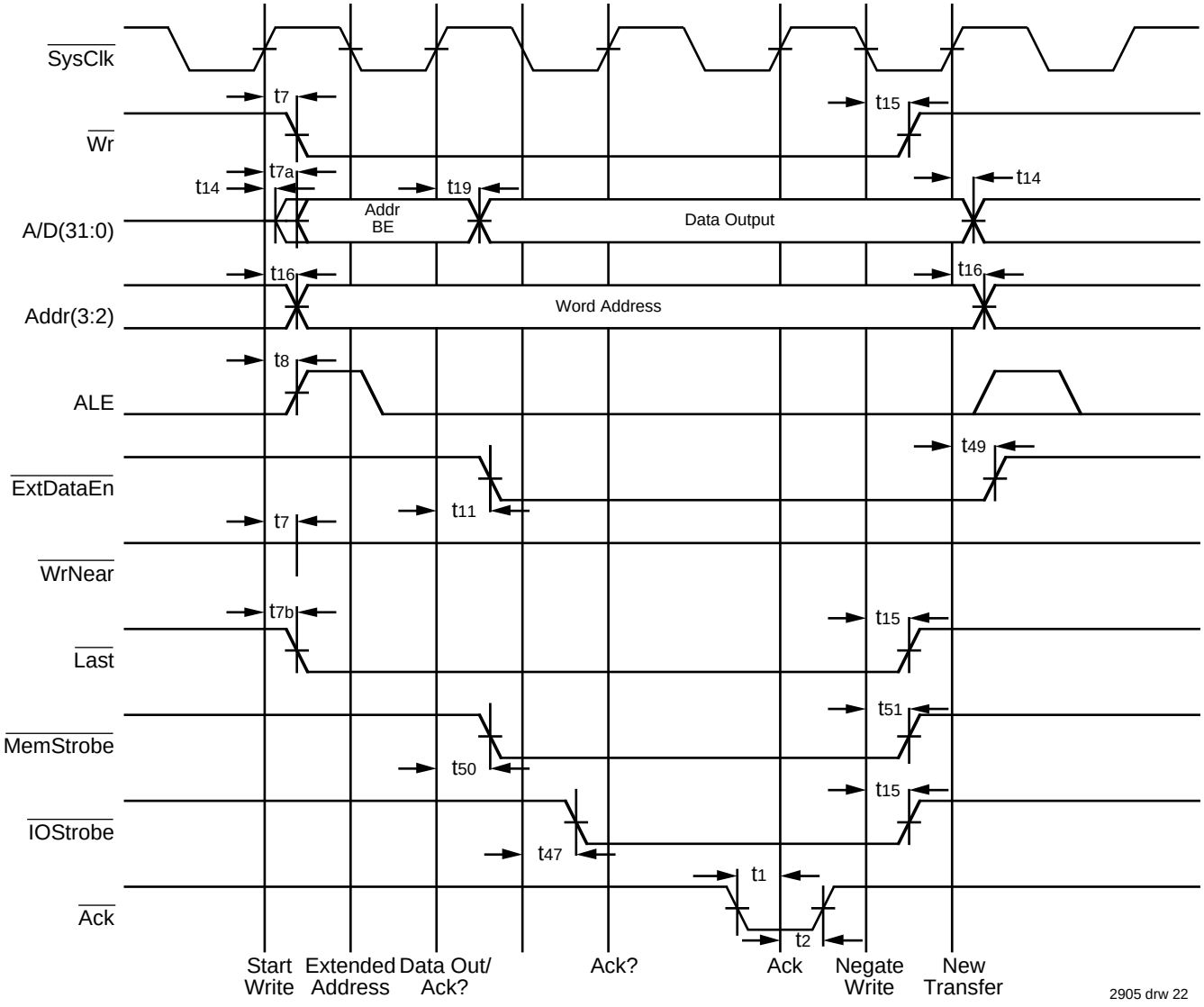


Figure 17. Basic Write to 32-bit Memory Port

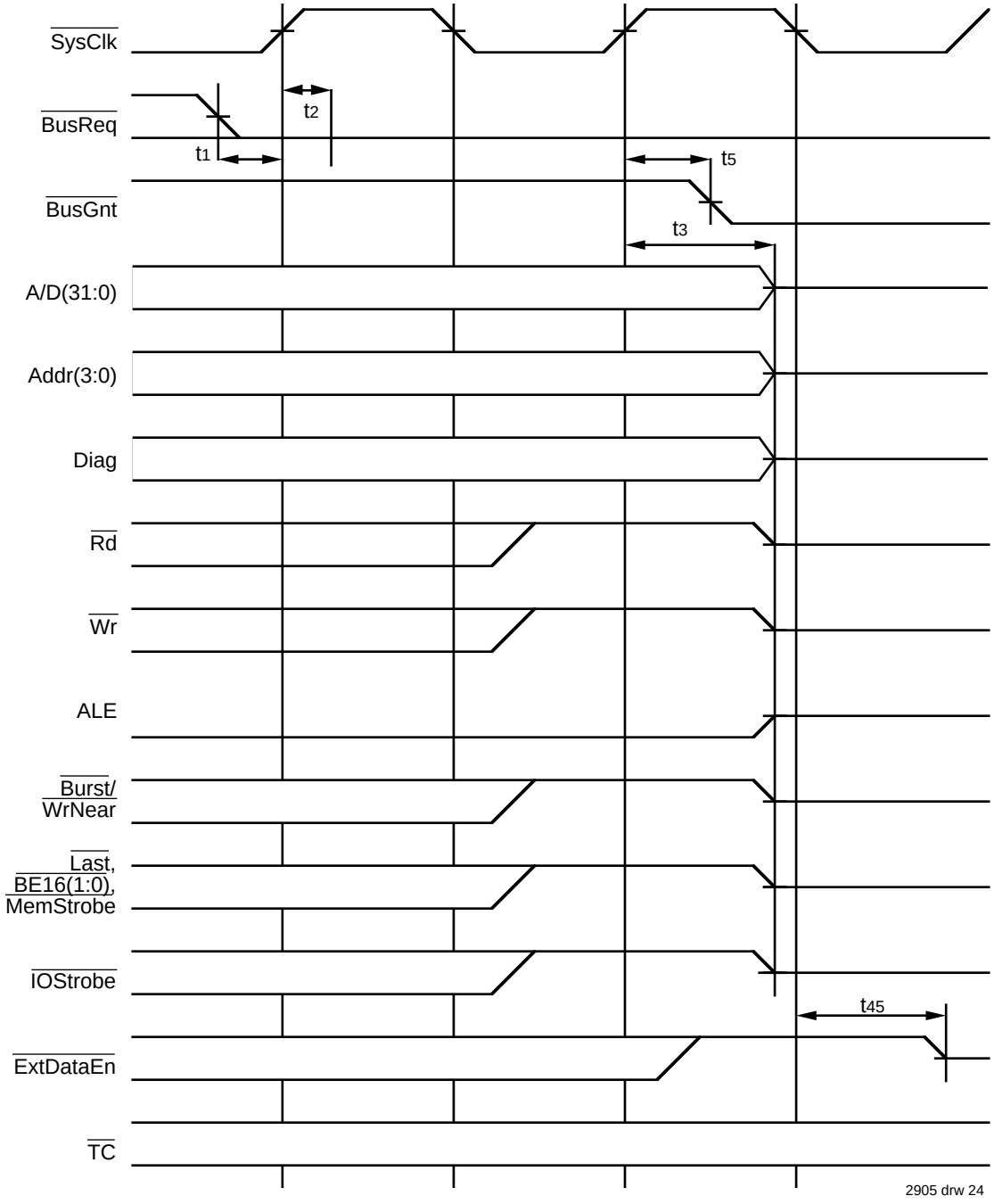


Figure 19. Request and Relinquish of R3041 Bus to External Master

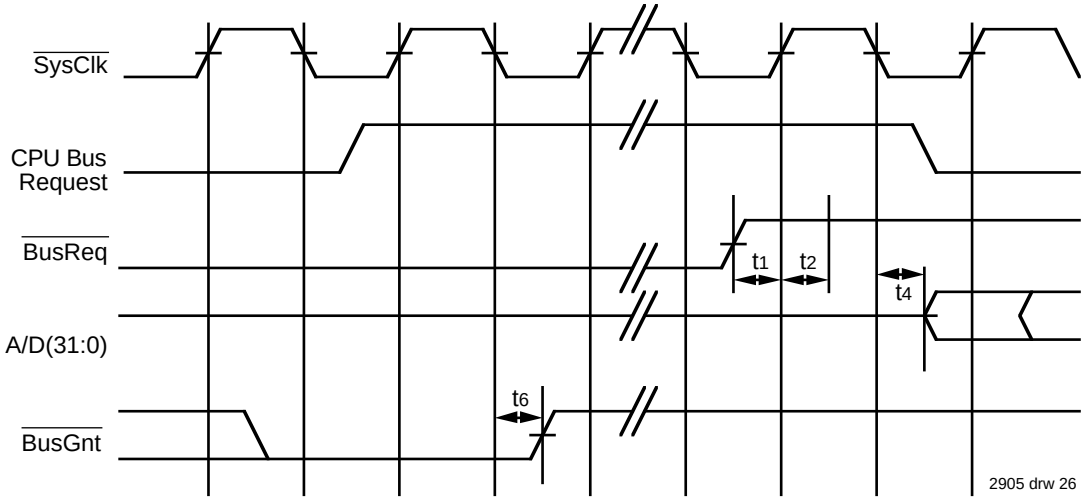


Figure 21. R3041 DMA Pulse Protocol

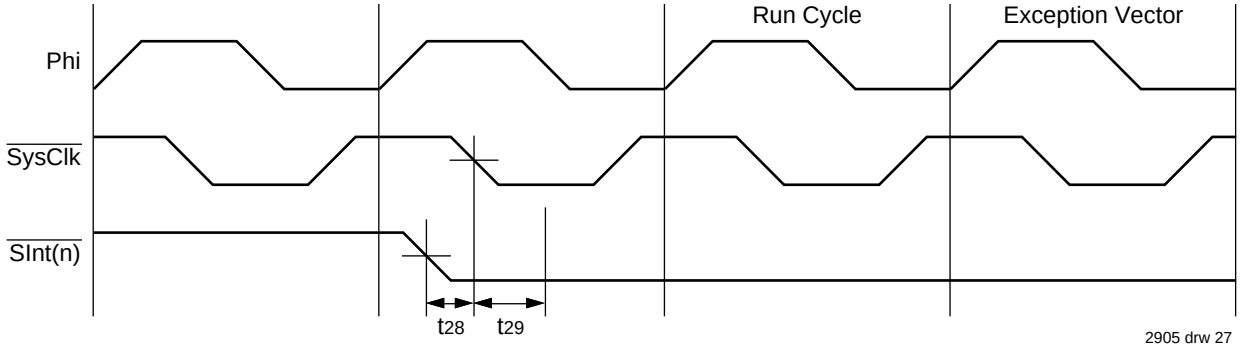


Figure 22. Synchronized Interrupt Input Timing

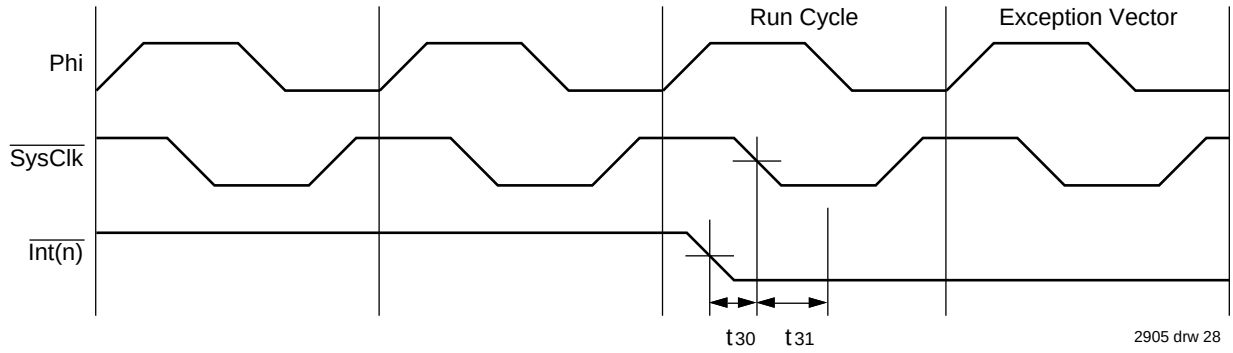


Figure 23. Direct Interrupt Input Timing

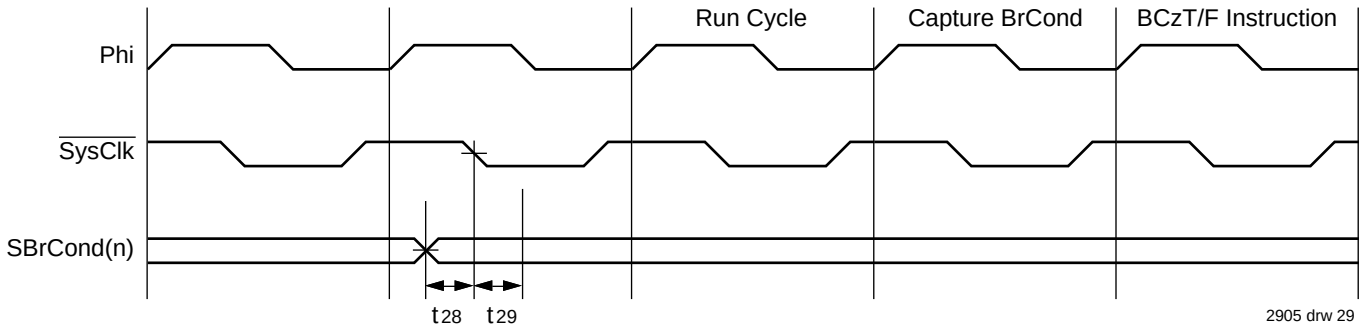


Figure 24. Synchronized Branch Condition Input Timing

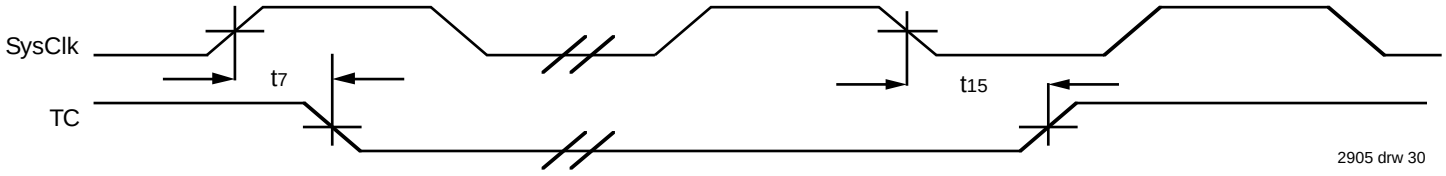
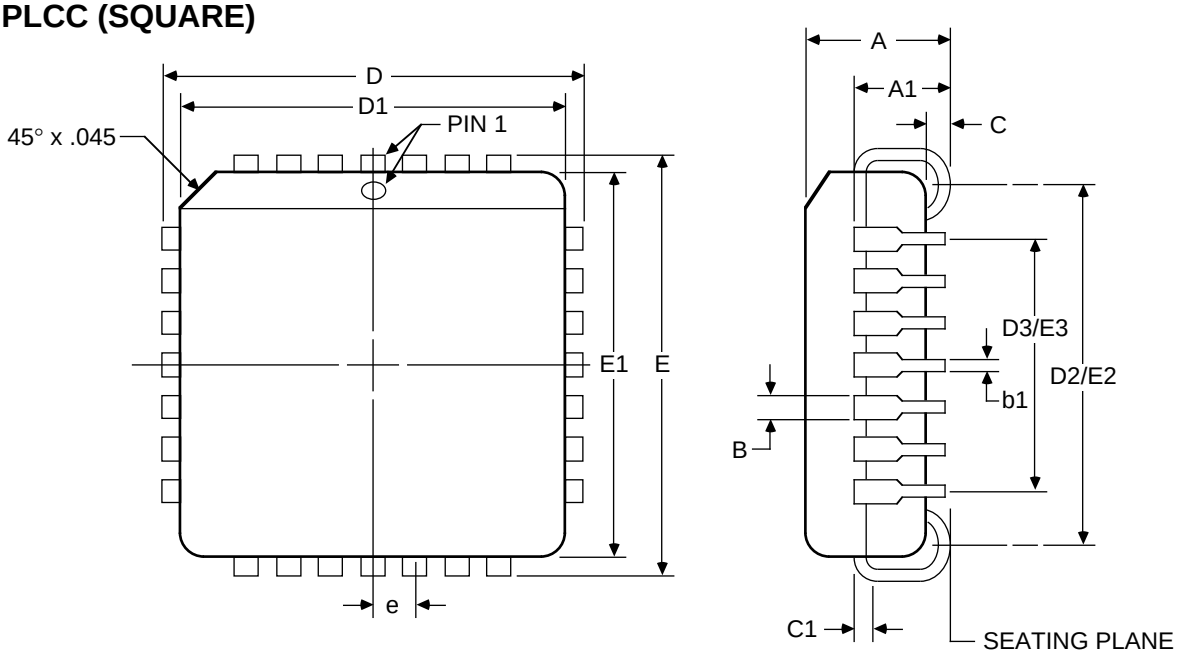


Figure 25. $\overline{TC}$ Output

84 LEAD PLCC (SQUARE)

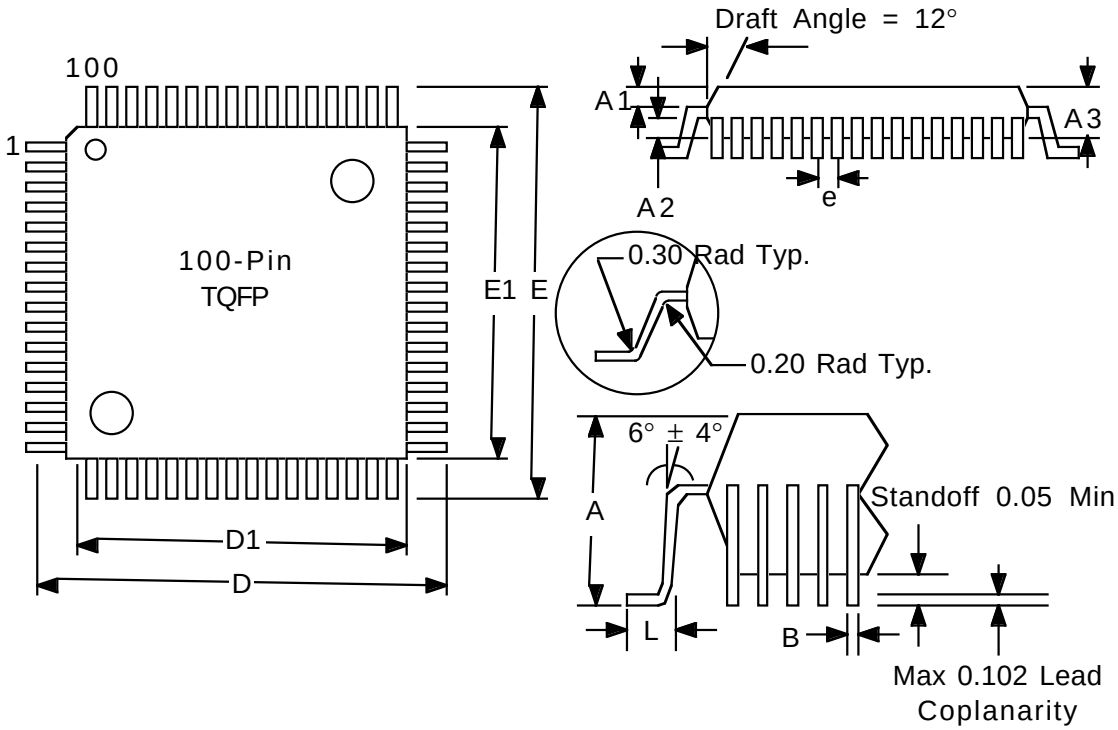


DWG #	J84-1	
# of Leads	84	
Symbol	Min.	Max.
A	165	.180
A1	.095	.115
B	.026	.032
b1	.013	.021
C	.020	.040
C1	.008	.012
D	1.185	1.195
D1	1.150	1.156
D2/E2	1.090	1.130
D3/E3	1.000 REF	
E	1.185	1.195
E1	1.150	1.156
e	.050 BSC	
ND/NE	21	

2905 tbl 13

NOTES:
1. All dimensions are in inches, unless otherwise noted.
2. BSC—Basic lead Spacing between Centers.
3. D & E do not include mold flash or protutions.
4. Formed leads shall be planar with respect to one another and within .004" at the seating plane.
5. ND & NE represent the number of leads in the D & E directions respectively.
6. D1 & E1 should be measured from the bottom of the package.
7. PLCC is pin & form compatible with MQUAD; the MQUAD package is used in other RISController family members.

100-PIN TQFP



DWG #	TQFP	
# of Leads	100	
Symbol	Min.	Max.
A	—	1.60
A1	0.5	0.15
A2	1.35	1.45
D	15.75	16.25
D1	13.95	14.05
E	15.75	16.25
E1	13.95	14.05
L	0.45	0.70
N	100	
e	0.50BSC	
b	0.17	0.27
ccc	—	0.08
ddd	—	0.08
R	0.08	0.20
R1	0.08	—
θ	0	7.0
θ1	11.0	13.0
θ2	11.0	13.0
c	0.09	0.16

2905 tbl 14